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03500.013918

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
YOSHIHIRO YANAGISAWA) : Examiner: J. Williams
Application No.: 09/722,705) : Group Art Unit: 2879
Filed: November 28, 2000) :
For: PRODUCTION METHOD OF)
IMAGE-FORMING APPARATUS, :
AND IMAGE-FORMING)
APPARATUS PRODUCED BY THE :
PRODUCTION METHOD) October 4, 2004

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THE COMMISSIONER FOR PATENTS
P.O. Box 1450
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LETTER

Sir:

In the Information Disclosure Statement filed on January 7, 2004, in the above-identified patent application, Applicant disclosed Japanese Laid-Open Patent Application Nos. 9-138509; 9-274847; 10-326558; and 9-22671.

The Examiner indicated consideration of those documents by returning an initialed copy of the Form PTO-1449 accompanying that Information Disclosure Statement.

Recently, Applicant received an Official Letter issued in a counterpart Japanese patent application. The Official Letter cites and discusses the above-listed Japanese patent applications. For the Examiner's reference, Applicant notes that the Japanese Patent Examiner's comments on those Japanese patent applications are generally as follows:

JP 9-138509 discloses a method of forming an upper electrode layer (corresponding to a wiring) by printing a predetermined expanding pattern of a resist material in which gold particles are dispersed according to a screen printing, and by subjecting it to an exposure, a development and baking into the electrode layer. Accordingly, it is well-known technique to form first and second electrodes, even without citing relating document.

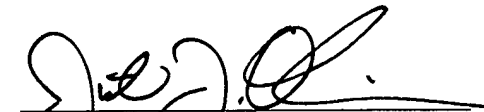
JP 9-274847 and JP 10-326558 disclose forming an electroconductive film according to an ink jet method. JP 9-274847 discloses a design of X-directional wiring at an interval of approximately 350 μ m, and Y-directional wiring at an interval of approximately 270 μ m (see column [0069]). JP 10-326658 discloses arrangement of electron-emitting devices at a pitch 270 μ m in the X-direction and at a pitch 840 μ m in the Y-direction (see column [0112 and [0117]). Thus, wiring interval is larger in X-direction than in Y-direction.

JP 9-22671 discloses a design of a first wiring of width 100 μ m and thickness 12 μ m, and a design of a second wiring of width 300 μ m and thickness 20 μ m (Embodiment 1). It is arbitrary to set the first and second wirings as any of X-directional and Y-directional wirings (see column [0038]).

In addition, for the Examiner's convenience, enclosed herewith are English translations of JP 9-138509 and JP 9-22671.

Applicant's undersigned attorney may be reached in our Washington, D.C. office by telephone at (202) 530-1010. All correspondence should continue to be directed to our below-listed address.

Respectfully submitted,


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